

Contents

- 1 Introduction 1**

- 2 Materials and Device Degradation. 5**
 - 1 Material/Device Parameter Degradation Modeling. 5
 - 1.1 Material/Device Parameter Decreases with Time. 6
 - 1.2 Material/Device Parameter Increases with Time 9
 - 2 General Time-Dependent Degradation Models 12
 - 3 Degradation Rate Modeling 13
 - 4 Delays in the Start of Degradation 15
 - 5 Competing Degradation Mechanisms. 19

- 3 From Material/Device Degradation to Time-to-Failure. 29**
 - 1 Time-to-Failure. 29
 - 2 Time-to-Failure Kinetics 32

- 4 Time-to-Failure Modeling. 37**
 - 1 Flux-Divergence Impact on Time-to-Failure. 37
 - 2 Stress Dependence and Activation Energy 40
 - 3 Conservative Time-to-Failure Models 45
 - 4 Time-to-Failure Modeling Under High-Stress 46
 - Bibliography 49

- 5 Gaussian Statistics: An Overview 51**
 - 1 Normal Distribution. 51
 - 2 Probability Density Function 53
 - 3 Statistical Process Control 56
 - Bibliography 60

- 6 Time-to-Failure Statistics 61**
 - 1 Lognormal Probability Density Function 61
 - 2 Weibull Probability Density Function 65

3	Multimodal Distributions	67
3.1	Multimodal Distribution (Separated in Time)	67
3.2	Mixed Multiple Failure Mechanisms	70
	Bibliography	74
7	Failure Rate Modeling	75
1	Device Failure Rate.	75
2	Average Failure Rate.	76
2.1	Lognormal Average Failure Rate.	77
2.2	Weibull Average Failure Rate.	77
3	Instantaneous Failure Rate	79
3.1	Lognormal Instantaneous Failure Rate	79
3.2	Weibull Instantaneous Failure Rate	79
4	Bathtub Curve	81
5	Failure Rate for Electronic Devices.	82
	Bibliography	89
8	Accelerated Degradation.	91
1	Metastable States	91
2	Impact of Temperature on Degradation Rate	93
3	Free Energy of Activation	95
4	Impact of Stress and Temperature on Degradation Rate.	96
4.1	Real Versus Virtual Stresses	96
4.2	Impact of Stress on Materials/Devices	97
5	Accelerated Degradation Rates	100
	Bibliography	103
9	Acceleration Factor Modeling	105
1	Acceleration Factor	105
2	Power-Law Versus Exponential Acceleration	108
3	Cautions Associated with Accelerated Testing	110
4	Conservative Acceleration Factors.	110
	Bibliography	115
10	Ramp-to-Failure Testing.	117
1	Ramp-to-Failure Testing	117
2	Linear Ramp Rate.	118
2.1	Linear Ramp with Exponential Acceleration	118
2.2	Linear Ramp with Power-Law Acceleration	120
3	Breakdown/Rupture Distributions	122
4	Cautions for Ramp-to-Failure Testing	124
5	Transforming Breakdown/Rupture Distributions into Constant-Stress Time-to-Failure Distributions	125

5.1	Transforming Breakdown/Rupture Distribution to Time-to-Failure Distribution Using Exponential Acceleration	125
5.2	Transforming Breakdown/Rupture Distribution to Time-to-Failure Distribution Using Power-Law Acceleration	126
6	Constant-Stress Lognormal Time-to-Failure Distributions from Ramp Breakdown/Rupture Data	126
6.1	Exponential Acceleration	126
6.2	Power-Law Acceleration.	127
7	Constant-Stress Weibull Time-to-Failure Distributions from Ramp Breakdown/Rupture Data	127
7.1	Exponential Acceleration	128
7.2	Power-Law Acceleration.	128
	Bibliography	132
11	Time-to-Failure Models for Selected Failure Mechanisms in Integrated Circuits	133
1	Electromigration	133
2	Stress Migration	142
2.1	SM in Aluminum Interconnects.	143
2.2	SM in Cu Interconnects	146
3	Corrosion	150
3.1	Exponential Reciprocal-Humidity Model	154
3.2	Power-Law Humidity Model.	155
3.3	Exponential Humidity Model	155
4	Thermal-Cycling/Fatigue Issues	156
5	Time-Dependent Dielectric Breakdown	161
5.1	Exponential E-Model	161
5.2	Exponential 1/E-Model.	164
5.3	Power-Law Voltage V-Model	165
5.4	Exponential \sqrt{E} -Model	165
5.5	Which TDDDB Model to Use?	165
5.6	Complementary Electric Field and Current-Based Models	168
6	Mobile-Ions/Surface-Inversion	171
7	Hot-Carrier Injection	173
8	Negative-Bias Temperature Instability	178
	Bibliography	186
12	Time-to-Failure Models for Selected Failure Mechanisms in Mechanical Engineering	193
1	Molecular Bonding in Materials	193
2	Origin of Mechanical Stresses in Materials	197

3	Elastic Behavior of Materials	198
4	Inelastic/Plastic Behavior of Materials	202
5	Important Defects Influencing Material Properties.	205
5.1	Vacancies	205
5.2	Dislocations	206
5.3	Grain Boundaries.	209
6	Fracture Strength of Materials	211
7	Stress Relief in Materials	213
8	Creep-Induced Failures	214
8.1	Creep Under Constant Load/Stress Conditions	215
8.2	Creep Under Constant Strain Conditions	223
9	Crack-Induced Failures	227
9.1	Stress Raisers/Risers at Crack Tips	228
9.2	Strain-Energy Release Rate.	230
9.3	Fast Fracture/Rupture.	232
10	Fatigue-Induced Failures	234
10.1	Fatigue for Materials (No Pre-Existing Cracks).	235
10.2	Low-Cycle Fatigue	235
10.3	High-Cycle Fatigue	236
10.4	Fatigue for Materials (With Pre-existing Cracks).	239
11	Adhesion Failures	241
12	Thermal-Expansion-Induced Failures.	242
12.1	Thermal Expansion	242
12.2	Constrained Thermal-Expansion	244
12.3	Thermal-Expansion Mismatch.	244
12.4	Thin Films on Thick Substrates.	246
13	Corrosion-Induced Failures.	248
13.1	Dry Oxidation	249
13.2	Wet Corrosion.	255
13.3	Impact of Stress on Corrosion Rates	259
	Bibliography	264
13	Conversion of Dynamical Stresses into Effective Static Values . . .	267
1	Effective Static-Stress Equivalent Values	267
2	Effective Static-Stress Equivalent Values When Using Power-Law TF Models	269
3	Effective Static-Stress Equivalent Values When Using Exponential TF Models	271
4	Conversion of a Dynamical Stress Pulse into a Rectangular Pulse Stress Equivalent	272
4.1	Effective Rectangular Pulse Stress-Equivalent Values for Power-Law TF Models	272
4.2	Effective Rectangular Pulse Stress-Equivalent Values for Exponential TF Models	273

4.3	Numerical Integration.	273
5	Effective Static Temperature Equivalents.	277
6	Mission Profiles	280
7	Avoidance of Resonant Frequencies	286
14	Increasing the Reliability of Device/Product Designs	291
1	Reliability Enhancement Factor	292
2	Electromigration Design Considerations.	292
3	TDDDB Design Considerations.	293
4	Negative-Bias Temperature Instability Design Considerations. . .	294
5	HCI Design Considerations	294
6	Surface Inversion Design Considerations	295
7	Creep Design Considerations	295
7.1	Creep in Rotors.	296
7.2	Creep in Pressurized Vessels.	297
7.3	Creep in a Leaf Spring.	297
7.4	Stress Relaxation in Clamps/Fasteners	298
8	Fatigue Design Considerations	299
8.1	Fatigue in Storage Vessels	299
8.2	Fatigue in Integrated Circuits (ICs)	300
15	Screening	303
1	Breakdown/Strength Distribution for Materials and Devices. . .	303
2	Impact of Screening Stress on Breakdown Strength.	304
2.1	Screening Using Exponential TF Model	305
2.2	Screening Using Power-Law TF Model	307
3	Screening Effectiveness	309
3.1	Screening Effectiveness Using Exponential TF Model . .	310
3.2	Screening Effectiveness Using Power-Law TF Model . .	313
16	Heat Generation and Dissipation.	319
1	Device Self-Heating and Heat Transfer	319
1.1	Energy Conservation	320
1.2	General Heat Flow Equation.	322
2	Steady-State Heat Dissipation.	324
3	Effective Thermal Resistance	327
4	General Transient Heating and Heat Dissipation.	331
4.1	Effective Thermal Resistance Revisited	332
4.2	Heat Capacity	333
5	Modeling Dynamical Heat Generation and Dissipation	333
5.1	Thermal Relaxation	335
5.2	Thermal Rise with Constant Input Power	338
5.3	Thermal Rise and Relaxation with Single Power Pulse. . .	339

5.4	Thermal Rises and Relaxations with Periodic Power Pulses	339
6	Convection Heat Transfer	344
7	Radiation Heat Transfer	346
8	Entropy Changes Associated with Heat Transfer	348
	Bibliography	353
17	Sampling Plans and Confidence Intervals	355
1	Poisson Distribution	355
1.1	Poisson Probability for Finding Defective Devices	356
1.2	Poisson Sample Size Requirements	358
2	Binomial Distribution	360
2.1	Binomial Probability for Finding Defective Devices	360
2.2	Binomial Sample Size Requirements	361
3	Chi Square Distribution	363
3.1	Chi Square Confidence Intervals	363
3.2	Chi Square Distribution for Defect Sampling	364
4	Confidence Intervals for Characteristic Time-to-Failure and Dispersion Parameters	367
4.1	Normal Distribution Confidence Intervals	367
4.2	Lognormal Distribution Confidence Intervals	368
4.3	Weibull Distribution Confidence Intervals	370
4.4	Chi Square Distribution Confidence Intervals for Average Failure Rates	372
	Bibliography	376
	Appendices	377
	Index	391



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